

# Agilent HSMF-C118 TriColor ChipLED

## Data Sheet



### Description

The HSMF-C118 tricolor chip-type LED is designed in an ultra small package for miniaturization. It is the first of its kind to achieve such small packaging for 3 dies. With the freedom to have any combination of colors from mixing of the 3 primary colors, this will yield a wide variety of colors to suit every application and product theme.

The small size, narrow footprint, and low profile make this LED excellent for back-lighting, status indication, and front panel illumination applications.

In order to facilitate pick and place operation, this ChipLED is shipped in tape and reel, with 3000 units per reel. The package is compatible with IR soldering and binned by both color and intensity.

### Features

- Common anode
- Small 3.2 x 2.7 x 1.1 mm package
- Diffused optics
- Red/Green/Blue color combination
- Available in 8 mm tape on 7 inch (178 mm) diameter reels
- High brightness using AlInGaP and InGaN die technology
- Compatible with reflow soldering

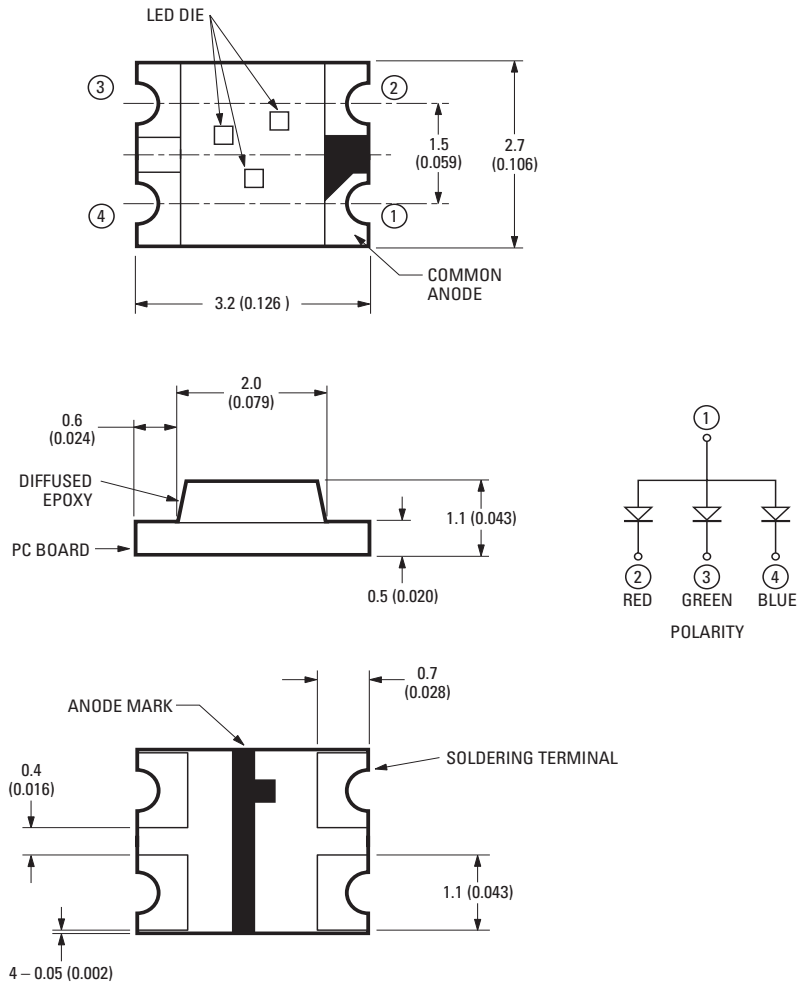
### Applications

- Backlighting
- Status indicator
- Front panel indicator
- Office automation, home appliances, industrial equipment

**CAUTION:** HSMF-C118 is Class 1 ESD sensitive per MIL-STD-1686. Please observe appropriate precautions during handling and processing. Refer to Agilent Technologies Application Note AN-1142 for additional details.



## Package Dimensions



- NOTES:  
 1. DIMENSIONS IN MILLIMETERS (INCHES).  
 2. TOLERANCE  $\pm 0.1$  mm UNLESS OTHERWISE NOTED.

### Absolute Maximum Ratings at T<sub>A</sub> = 25° C

Parameter	AllInGaP Red	InGaN Green	InGaN Blue	Units
DC Forward Current <sup>[1, 3, 4]</sup>	20	20	20	mA
Power Dissipation <sup>[1]</sup>	48	78	78	mW
DC Forward Current <sup>[2]</sup>	15	15	15	mA
Power Dissipation <sup>[2]</sup>	36	59	59	mW
Reverse Voltage (I <sub>R</sub> = 100 μA)	5	5	5	V
LED Junction Temperature	95	95	95	°C
Operating Temperature Range	-40 to +85			°C
Storage Temperature Range	-40 to +85			°C
Soldering Temperature	See reflow soldering profile (Figures 6 & 7)			

#### Notes:

1. Applies when single LED is lit up.
2. Applies when all 3 LEDs are lit up simultaneously.
3. Derate linearly as shown in Figure 4.
4. Drive currents above 5 mA are recommended for best long term performance.

### Electrical Characteristics at T<sub>A</sub> = 25° C

Color	Forward Voltage V <sub>F</sub> (Volts) @ I <sub>F</sub> = 20 mA		Reverse Breakdown V <sub>R</sub> (Volts) @ I <sub>R</sub> = 100 μA	Capacitance C (pF), @ V <sub>F</sub> = 0, f = 1 MHz	Thermal Resistance R <sub>θJ-PIN</sub> (°C/W)
	Typ.	Max.	Min.	Typ.	Typ.
AllInGaP Red	1.9	2.4	5	17	400
InGaN Green	3.5	3.9	5	110	450
InGaN Blue	3.5	3.9	5	110	450

### Optical Characteristics at T<sub>A</sub> = 25° C

Color	Luminous Intensity I <sub>v</sub> (mcd) @ I <sub>F</sub> = 20 mA <sup>[1]</sup>		Peak Wavelength λ <sub>peak</sub> (nm)	Color, Dominant Wavelength λ <sub>d</sub> <sup>[2]</sup> (nm)	Viewing Angle 2 θ <sub>1/2</sub> Degrees <sup>[3]</sup>	Luminous Efficacy η <sub>v</sub> (lm/W)
	Min.	Typ.	Typ.	Typ.	Typ.	Typ.
AllInGaP Red	28.5	90	637	626	135	155
InGaN Green	45.0	120	523	525	130	490
InGaN Blue	11.2	40	468	470	125	80

#### Notes:

1. The luminous intensity, I<sub>v</sub>, is measured at the peak of the spatial radiation pattern which may not be aligned with the mechanical axis of the lamp package.
2. The dominant wavelength, λ<sub>d</sub>, is derived from the CIE Chromaticity Diagram and represents the perceived color of the device.
3. θ<sub>1/2</sub> is the off-axis angle where the luminous intensity is 1/2 the peak intensity.

#### CAUTION:

1. The above optical performance specifications are valid in the case when single LED is lit up.
2. The above product specifications DO NOT provide any guarantee on color mixing, color consistency over time, or uniformity in luminous intensity when more than 1 LED is lit.
3. Please refer to Agilent Technologies' *Application Brief AB D-007* for additional details/explanation on driving the part in parallel circuit.

### Intensity ( $I_V$ ) Bin Limits<sup>[1]</sup>

Bin ID	Intensity (mcd)	
	Min.	Max.
L	11.20	18.00
M	18.00	28.50
N	28.50	45.00
P	45.00	71.50
Q	71.50	112.50
R	112.50	180.00
S	180.00	285.00

Tolerance:  $\pm 15\%$ .

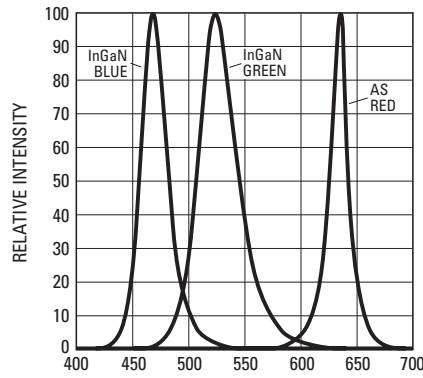


Figure 1. Relative intensity vs. wavelength.

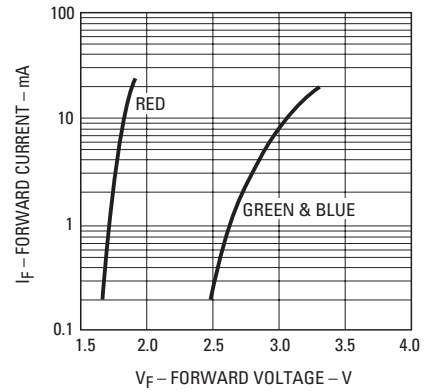


Figure 2. Forward current vs. forward voltage.

### Color Bin Limits<sup>[1]</sup>

Blue Color Bins		
Dom. Wavelength (nm)		
Bin ID	Min.	Max.
A	460.0	465.0
B	465.0	470.0
C	470.0	475.0
D	475.0	480.0

Tolerance:  $\pm 1$  nm

Red Color Bins		
Dom. Wavelength (nm)		
Bin ID	Min.	Max.
—	615.0	630.0

Tolerance:  $\pm 1$  nm

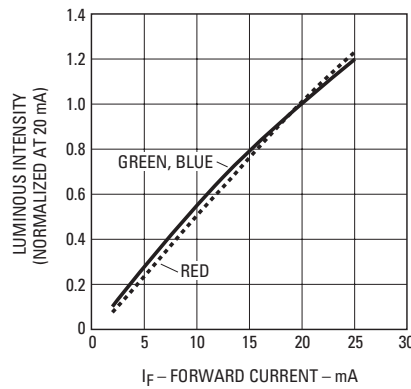


Figure 3. Luminous intensity vs. forward current.

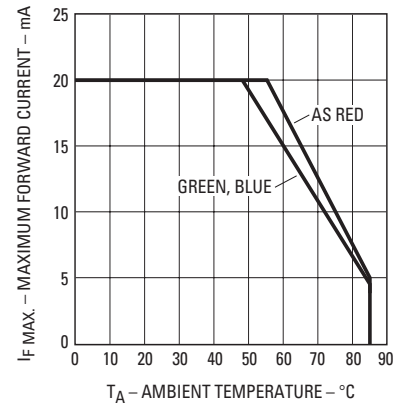


Figure 4. Maximum forward current vs. ambient temperature (1 chip lit up).

Green Color Bins		
Dom. Wavelength (nm)		
Bin ID	Min.	Max.
A	515.0	520.0
B	520.0	525.0
C	525.0	530.0
D	530.0	535.0

Tolerance:  $\pm 1$  nm

### Note:

- Bin categories are established for classification of products. Products may not be available in all categories. Please contact your Agilent representative for information on currently available bins.

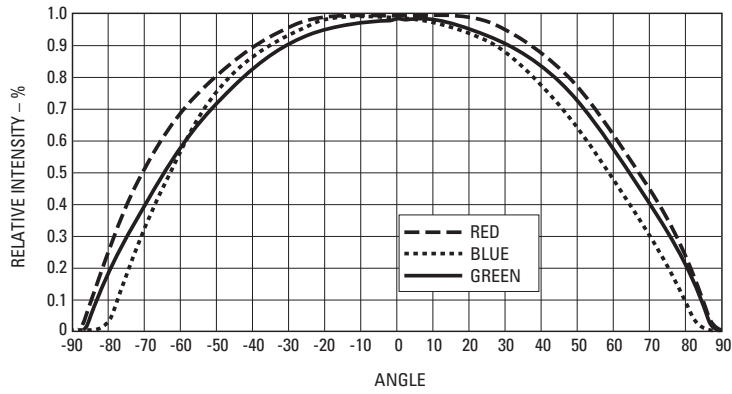


Figure 5. Relative intensity vs. angle.

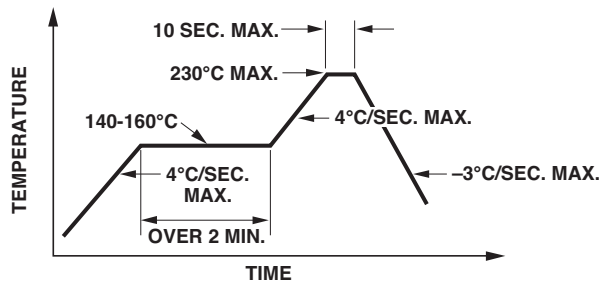


Figure 6. Recommended Pb-Free reflow soldering profile.

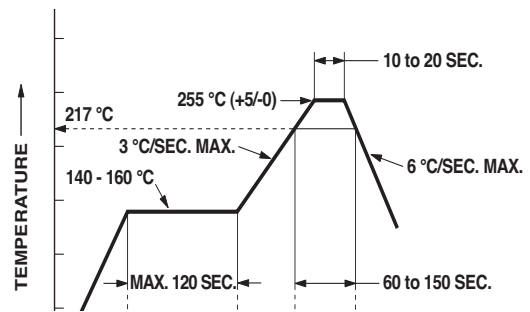


Figure 7. Recommended Pb-Free reflow soldering profile.

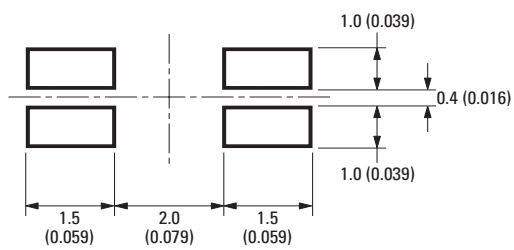


Figure 8. Recommended soldering pattern.

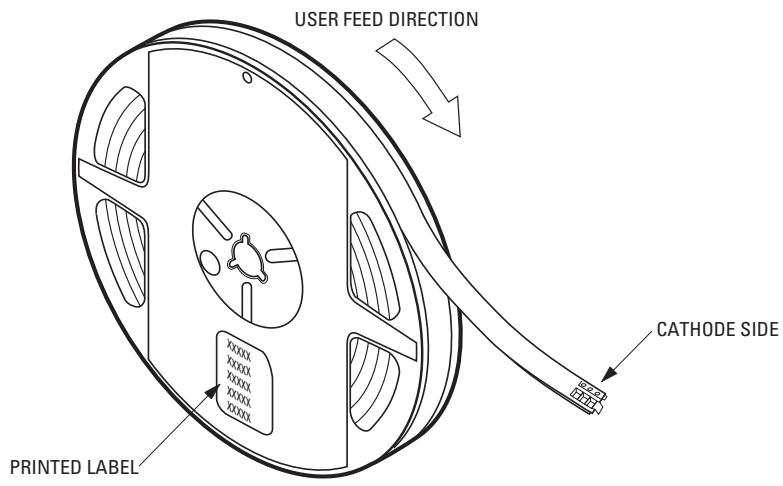


Figure 9. Reeling orientation.

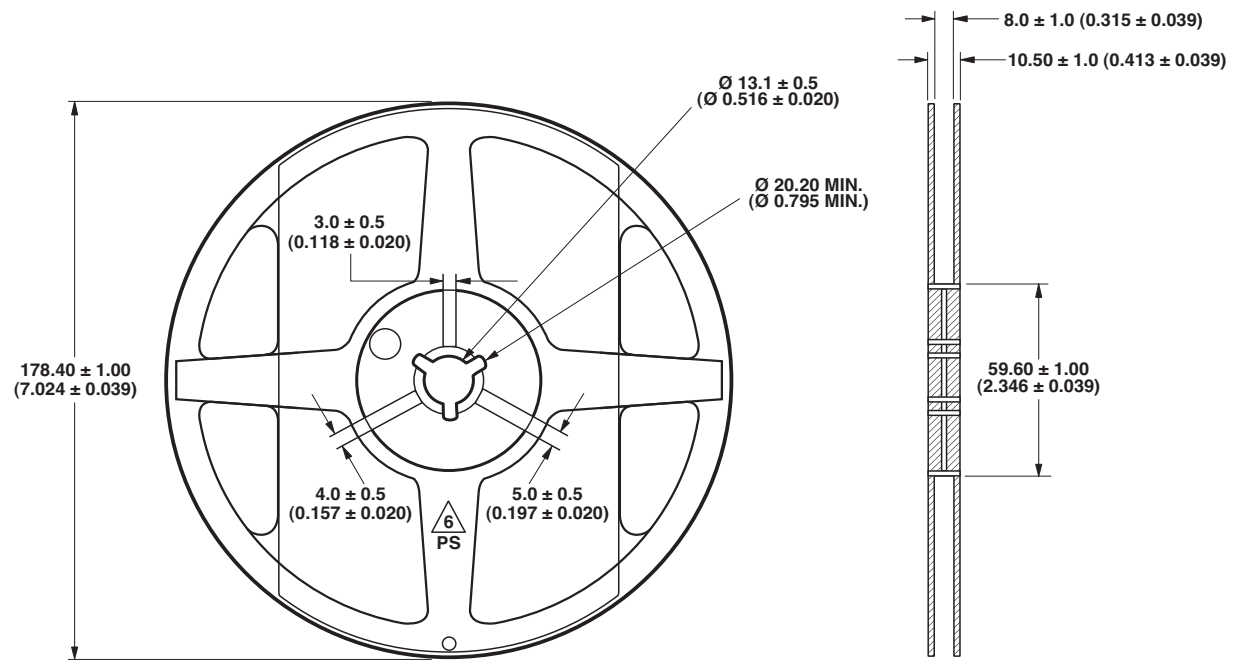


Figure 10. Reel dimensions.

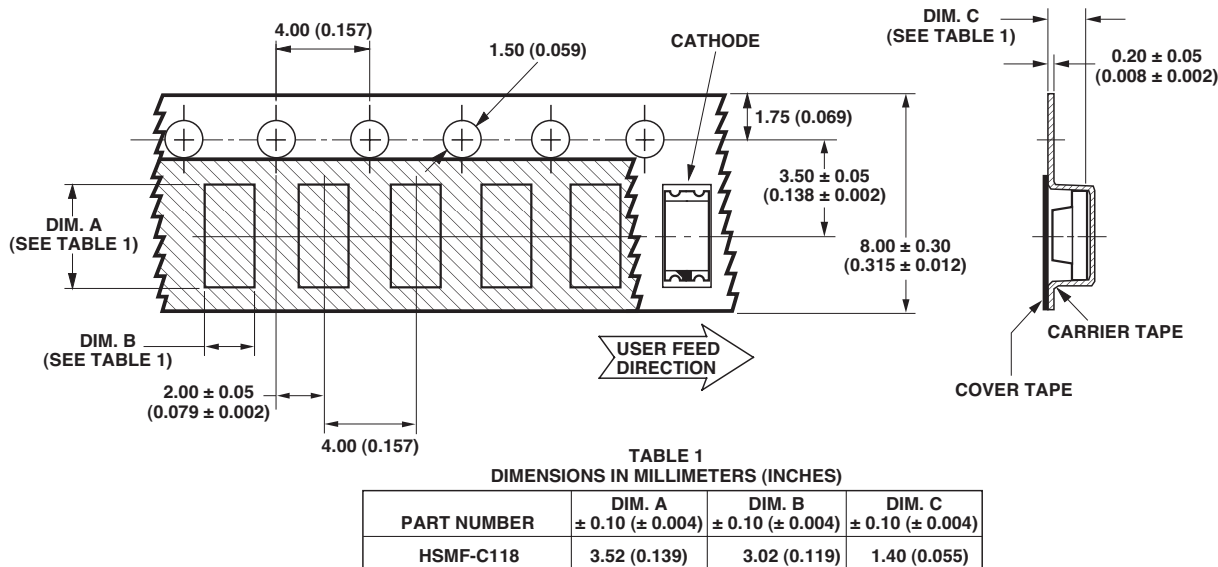


Figure 11. Tape dimensions.

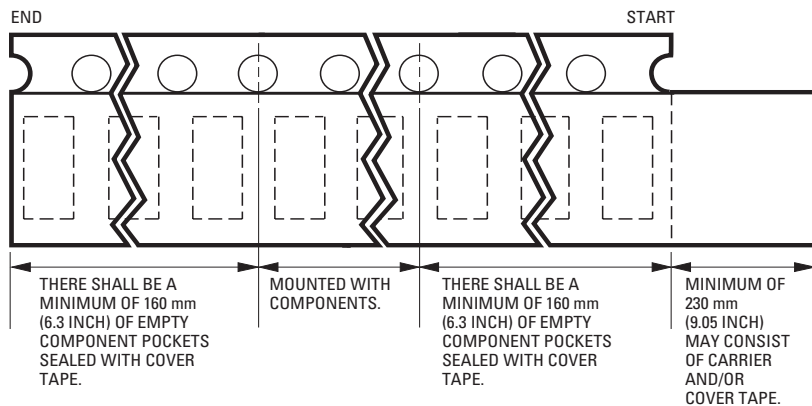


Figure 12. Tape leader and trailer dimensions.

NOTE:

1. ALL DIMENSIONS IN MILLIMETERS (INCHES).

**Convective IR Reflow Soldering**

For more information on IR reflow soldering, refer to Application Note 1060, *Surface Mounting SMT LED Indicator Components*.

**Storage Condition:**

5 to 30°C @ 60% RH max.

Baking is required under the condition:

- a) the blue silica gel indicator becoming white/transparent color
- b) the pack has been opened for more than 1 week

Baking recommended condition: 60 ± 5°C for 20 hours.

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